

H253-Z10-AAP1

High Density Server - 2U 4-Node UP 8-Bay E1.S



Features

- 2U 4-node front access server system
- Single AMD EPYC™ 9005/9004 Series Processors per node
- 12-Channel DDR5 RDIMM, 24 x DIMMs per node
- Dual ROM Architecture
- 8 x 1Gb/s LAN ports via Intel® I350-AM2
- 2 x CMC ports
- 8 x E1.S Gen4 NVMe hot-swap bays
- 12 x M.2 slots with PCIe Gen5 x4 and SATA interface
- 4 x LP PCIe Gen5 x16 slots
- 4 x OCP NIC 3.0 PCIe Gen5 x16 slots
- Dual 3000W 80 PLUS Titanium redundant power supply

Application

HPC, HCI, Hybrid/Private Cloud Server

Specification

Dimensions	2U 4-Node - Front access (W447 x H86.8 x D902 mm)	I/O ports	Front: 8 x USB 3.2 Gen1, 4 x Mini-DP, 8 x RJ45, 4 x MLAN Rear: 2 x CMC
Motherboard	MZ13-SH0	TPM	1 x TPM headers with SPI interface (per node) - Optional TPM2.0 kit: CTM010
CPU	AMD EPYC™ 9005/9004 Series Processors Single processor per node, cTDP up to 300W - At ambient 30°C, cTDP up to 400W	Power Supply	Dual 3000W 80 PLUS Titanium redundant power supply AC Input: 100-240V *The system power supply requires C19 power cord.
Socket	4 x LGA 6096 (Socket SP5)	System Management	ASPEED® AST2600 Baseboard Management Controller ASPEED® AST2520 Chassis Management Controller GIGABYTE Management Console web interface
Chipset	System on Chip	OS Support	Windows Server, Red Hat Enterprise Linux server, Ubuntu, SUSE Linux Enterprise server, VMware ESXi, Citrix Hypervisor
Memory	12-Channel DDR5 RDIMM, 96 x DIMMs [EPYC 9005] Up to 5200 MT/s (1DPC), Up to 4400 MT/s (1R 2DPC), 4000 MT/s (2R 2DPC) [EPYC 9004] Up to 4800 MT/s (1DPC), 3600 MT/s (2DPC)	System Fans	4 x 80x80x80mm (16,500rpm)
LAN	8 x 1Gb/s LAN ports (Intel® I350-AM2) - Support NCSI function 4 x 10/100/1000 management LAN 2 x CMC ports	Operating Properties	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
Video	Integrated in ASPEED® AST2600 x 4 - 4 x Mini-DP	Packaging Content	1 x H253-Z10-AAP1, 4 x CPU heatsinks, 1 x L-shape Rail kit Packaging Dimensions: 1180 x 779 x 300 mm
Storage	Front hot-swap: 8 x 9.5mm E1.S Gen4 NVMe Internal M.2: 4 x M.2 (2280/22110), PCIe Gen5 x4 8 x M.2 (2280), SATA via ASM1062R - Support SATA HW RAID 0/1	Part Numbers	Barebone package: 6NH253Z10DR000ACP1* Optional parts: - E1.S Latch with dummy tray (24 in 1): 6NH253Z10S1000AAP11 - C19 power cord 125V/15A (US): 25CP1-018000-Q0R - C19 power cord 250V/16A (EU): 25CP3-01830H-Q0R - C19 power cord 125V/15A (JP): 25CPA-01830B-Q0R - RMA packaging: 6NH253Z10SR-RMA-A100
SAS	N/A		
RAID	N/A		
Expansion Slots	4 x LP PCIe Gen5 x16 slots 4 x OCP NIC 3.0 PCIe Gen5 x16 slots		



Learn more at <https://www.GIGABYTE.com/enterprise>

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